defining a degree of excellence



10BASE-TNETWORK COMPONENTS

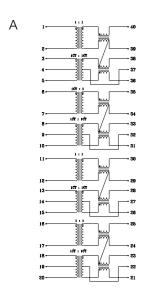
960064A

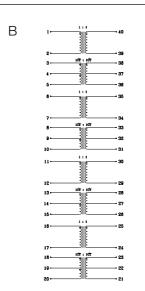
- Designed for use with AMD's elMR (79C984A), elMR+ (79C985) and IMR2 (79C983)/QuIET (79C988) chipsets
- Filterless quad, 4-port designs with common footprints and pinouts offering choice configurations for customized EMI suppression
- Best space and cost efficiency
- Low profile, surface mount packaging, rated to 225°C peak IR reflow temperature
- 2000 Vrms isolation

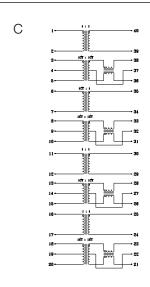
ELECTRICALS AT 25°C

Part No.	Insertion Loss (dB) Max 1-10MHz	OCL (µH) Min	Return Loss (dB) Min 5MHz-10MHz	Crosstalk (dB) Min 1MHz-10MHz	CM-CM (dB) N 10-30MHz	•	Schematic
S553-5999-25	-1.0	100	-18	-40	-40	-30	А
S553-5999-26	-1.0	100	-18	-40			В
S553-5999-32	-1.0	100	-18	-40	-40	-30	С

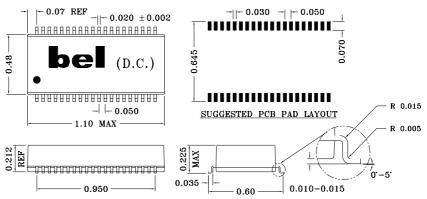
SCHEMATICS







MECHANICAL



Specifications subject to change without notice.

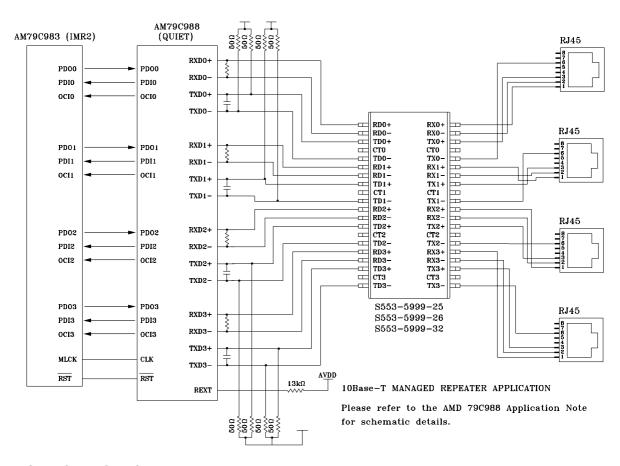


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10BASE-TNETWORK COMPONENTS

960064A

APPLICATION CIRCUIT



APPLICATION NOTES

- Bel has developed a variety of quad, 4-port part types for use with AMD's product line of quad, 4-port PHY transceivers that incorporate digital filtering techniques within the silicon itself. Bel's "filterless magnetics" are optimized for this specific application and create a very cost efficient design solution. Each Bel part type contains transmit and receive transformers to provide for wave shaping, high voltage isolation and EMI noise suppression.
- Bel has designed these parts as a family of parts with common footprint and pinouts to enable the designer to customize the use of common mode choke for optimum system performance.
- In multi-port system applications, good PCB layout and proper grounding techniques are very critical to achieve FCC class A and B equipment approvals. Bel recommendations are available and can be provided by contacting our engineering department or your local sales representative.
- Bel's low profile, surface mount packaging is ideal for high speed pick and place machinery. Parts can be shipped on tape and reel for high speed placement. Construction processes have been implemented for thermal compatibility with high temperature IR reflow assembly processing. Post dipping of leads assist with PC board solderability. Each part is optically inspected to meet rigid coplanarity requirements.

Corporate Office

Bel Fuse Inc.

198 Van Vorst Street, Jersey City, NJ 07302-4496 Tel: 201-432-0463

Fax: 201-432-9542

E-Mail: BelFuse@belfuse.com Internet: http://www.belfuse.com Far East Office

Bel Fuse Ltd. 8F/8 Luk Hop Street San Po Kong Kowloon, Hong Kong Tel: 852-2328-5515 Fax: 852-2352-3706 European Office
Bel Fuse Europe Ltd.

Preston Technology Management Centre Marsh Lane, Preston PR1 8UD Lancashire, U.K. Tel: 44-1772-556601 Fax: 44-1772-888366